

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by

Udo Steinebrunner, Product Manager, -

Declaration effective from: 02 January 2014 [Approved: 07 February 2025 11:43 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.23%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.5%
			ALUMINUM, ELEMENTAL	7429-90-5	1%
			GOLD, ELEMENTAL	7440-57-5	1%
			Elemental silicon	7440-21-3	97.5%
			Carbon black	1333-86-4	1%
			ALUMINUM(III) HYDROXIDE	21645-51-2	5%
Encapsulation	EP (Epoxy resin)	53.656%	Phenol, polymer with formaldehyde	9003-35-4	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
Inner preparation	Copper alloys	0.004%	Quartz sand	60676-86-0	79%
Leadfinish	Tin plating	13.32%	COPPER, ELEMENTAL	7440-50-8	100%
			Tin elemental	7440-31-5	100%
			SILVER, ELEMENTAL	7440-22-4	0.41%
			Elemental zinc	7440-66-6	0.52%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	32.79%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.7%
			Tin elemental	7440-31-5	1%
			COPPER, ELEMENTAL	7440-50-8	97.37%

Attached parts list

Part number	Part name
SOT-23/TO-236_Pb&H-free_(AO)_sin	Diode / Transistor SMD